



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-22
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L5963Q-V0T	A9V0*UAE2AEX	A	Z7GA	2016-06-22
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x1	48	flat	
Comment	Package: VFQFPN 7x7x1.0 48 PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AS90*UAEZAEX									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	10.007	mg	supplier	die	Silicon (Si)	7440-21-3		9.099	mg	909264	69992				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	2198	169				
				supplier	metallization	Copper (Cu)	7440-50-8		0.560	mg	55961	4308				
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	100	8				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	600	46				
				supplier	metallization	Tungsten (W)	7440-33-7		0.032	mg	3198	246				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.070	mg	6995	538				
				supplier	metallization	Platinum (Pt)	7440-06-4		0.039	mg	3897	300				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	1799	138				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.140	mg	13990	1077				
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	500	38				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	1399	108				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	100	8				
				Leadframe	Copper & its alloys	50.631	mg	supplier	alloy	Copper (Cu)	7440-50-8		49.261	mg	972941	378931
								supplier	alloy	Chromium (Cr)	7440-47-3		0.134	mg	2647	1031
supplier	alloy	Tin (Sn)	7440-31-5						0.124	mg	2449	954				
supplier	alloy	Zinc (Zn)	7440-66-6						0.099	mg	1955	762				
supplier	metallization	Silver (Ag)	7440-22-4						1.013	mg	20008	7792				
Other organic materials	4.568	mg	supplier					glue	Silver (Ag)	7440-22-4		3.723	mg	815018	28638	
			supplier					glue	(Octahydro-4,7-methano-1 H-indenediyl)bis(m	42594-17-2		0.274	mg	59982	2108	
			supplier					glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.274	mg	59982	2108	
			supplier					glue	isobornyl acrylate	5888-33-5		0.274	mg	59982	2108	
			supplier					glue	Bis(.alpha.,.alpha.-Dimethylbenzyl) peroxide	80-43-3		0.023	mg	5035	177	
Bonding wires	Precious metals	1.923	mg	supplier	wire	Gold (Au)	7440-57-5		1.923	mg	1000000	14792				
Encapsulation	Other organic materials	58.555	mg	supplier	mold compound	Silica, vitreous	60676-86-0		52.992	mg	904995	407631				
				supplier	mold compound	Epoxy Resin	25068-38-6		2.752	mg	46999	21169				
				supplier	mold compound	Phenol Resin	29960-82-2		2.752	mg	46999	21169				
				supplier	mold compound	Carbon black	1333-86-4		0.059	mg	1008	454				
Connections coating	Solder	4.316	mg	supplier	mold compound	Tin (Sn)	7440-31-5		4.316	mg	1000000	33200				